# onsemi

## IGBT – Power, Co-PAK N-Channel, Field Stop VII (FS7), SCR, TO247-3L 1200 V, 1.67 V, 40 A

# AFGHL40T120RWD-STD

#### Description

Using the novel field stop 7th generation IGBT technology and the Gen7 Diode in TO247 3–lead package, this device offers good performance with low on state voltage and low switching losses for both hard and soft switching topologies in automotive applications.

#### Features

- Extremely Efficient Trench with Field Stop Technology
- Maximum Junction Temperature  $T_J = 175^{\circ}C$
- Short Circuit Rated and Low Saturation Voltage
- Fast Switching and Tightened Parameter Distribution
- AEC-Q101 Qualified, PPAP Available Upon Request
- This Device is Pb–Free, Halogen Free/BFR Free and is RoHS Compliant

#### Applications

• Automotive E-compressor / Automotive EV PTC Heater / OBC

#### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

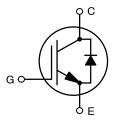
		-		1
Param	Symbol	Value	Unit	
Collector-to-Emitter Volta	V <sub>CE</sub>	1200	V	
Gate-to-Emitter Voltage		$V_{GE}$	±20	
Transient Gate-to-Emitte	er Voltage		±30	
Collector Current	$T_{C} = 25^{\circ}C$	۱ <sub>C</sub>	80	Α
	$T_{\rm C} = 100^{\circ}{\rm C}$		40	
Power Dissipation	$T_{\rm C} = 25^{\circ}{\rm C}$	PD	468	W
	$T_{\rm C} = 100^{\circ}{\rm C}$		234	
Pulsed Collector Current	T <sub>C</sub> = 25°C, tp = 10 μs (Note 1)	I <sub>CM</sub>	120	А
Diode Forward Current	$T_{\rm C} = 25^{\circ}{\rm C}$	١ <sub>F</sub>	80	
	$T_{\rm C} = 100^{\circ}{\rm C}$		40	
$ \begin{array}{l} \mbox{Pulsed Diode Maximum} \\ \mbox{Forward Current} \end{array}  \begin{array}{l} T_{C} = 25^{\circ}C, \\ \mbox{tp} = 10 \ \mu s \ (Note \ 1) \end{array} $		I <sub>FM</sub>	120	
Short Circuit Withstand T $V_{GE}$ = 15 V, $V_{CC}$ = 800 V,	T <sub>SC</sub>	6	μs	
Operating Junction and S Range	T <sub>J</sub> , T <sub>stg</sub>	– 55 to +175	°C	
Lead Temperature for Sol	Lead Temperature for Soldering Purposes			

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Repetitive rating: Pulse width limited by max. junction temperature

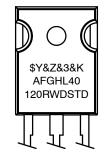
BV <sub>CES</sub>	V <sub>CE(sat)</sub> TYP	I <sub>C</sub> MAX
1200 V	1.67 V	40 A

## **PIN CONNECTIONS**





#### MARKING DIAGRAM



- \$Y = onsemi Logo
- &Z = Assembly Plant Code
- &3 = 3–Digit Date Code
- &K = 2-Digit Lot Traceability Code

AFGHL40120RWDSTD = Specific Device code

#### **ORDERING INFORMATION**

Device	Package	Shipping
AFGHL40T120RWD-STD	TO-247-3L (Pb-Free)	30 Units / Tube

#### THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case for IGBT	$R_{\theta JC}$	0.32	°C/W
Thermal Resistance, Junction-to-Case for Diode	$R_{\theta JCD}$	0.59	
Thermal Resistance, Junction-to-Ambient	$R_{ hetaJA}$	40	

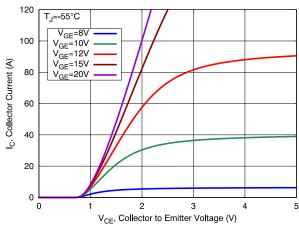
## **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS	<b>-</b>		-	-	-	-
Collector-to-Emitter Breakdown Voltage	BV <sub>CES</sub>	$V_{GE}$ = 0 V, I <sub>C</sub> = 1 mA	1200	-	_	V
Collector-to-Emitter Breakdown Voltage Temperature Coefficient	$\Delta BV_{CES}/\Delta T_{J}$	$V_{GE}$ = 0 V, I <sub>C</sub> = 9.99 mA	-	1226	-	mV/°C
Zero Gate Voltage Collector Current	I <sub>CES</sub>	$V_{GE}$ = 0 V, $V_{CE}$ = $V_{CES}$	-	-	40	μA
Gate-to-Emitter Leakage Current	I <sub>GES</sub>	$V_{GE}$ = ±20 V, $V_{CE}$ = 0 V	-	-	±400	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	V <sub>GE(th)</sub>	$V_{GE} = V_{CE}$ , $I_C = 40$ mA	5.1	6	6.9	V
Collector-to-Emitter Saturation	V <sub>CE(sat)</sub>	$V_{GE}$ = 15 V, I <sub>C</sub> = 40 A, T <sub>J</sub> = 25°C	-	1.67	2.00	V
Voltage		$V_{GE}$ = 15 V, $I_{C}$ = 40 A, $T_{J}$ = 175°C	-	2.12	-	1
DYNAMIC CHARACTERISTICS						
Input Capacitance	C <sub>IES</sub>	$V_{CE}$ = 30 V, $V_{GE}$ = 0 V, f = 1 MHz	-	3054	-	pF
Output Capacitance	C <sub>OES</sub>		-	126	-	1
Reverse Transfer Capacitance	C <sub>RES</sub>		-	15.4	-	
Total Gate Charge	Q <sub>G</sub>	$V_{CE}$ = 600 V, $V_{GE}$ = 15 V, $I_{C}$ = 40 A	-	112	-	nC
Gate-to-Emitter Charge	$Q_GE$		-	29.6	-	
Gate-to-Collector Charge	Q <sub>GC</sub>		-	51.2	-	
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	t <sub>d(on)</sub>		-	35.6	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>		-	188	-	1
Rise Time	t <sub>r</sub>		-	29.2	-	
Fall Time	t <sub>f</sub>		-	145	-	
Turn-On Switching Loss	E <sub>on</sub>		-	1.11	-	mJ
Turn-Off Switching Loss	E <sub>off</sub>		-	0.99	-	
Total Switching Loss	E <sub>ts</sub>		_	2.1	-	
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{CE} = 600 \text{ V}, V_{GE} = 15 \text{ V},$	-	40.1	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>	I <sub>C</sub> = 40 A, R <sub>G</sub> = 4.7 Ω, T <sub>J</sub> = 25°C	_	152	-	
Rise Time	t <sub>r</sub>		_	55.4	-	
Fall Time	t <sub>f</sub>		_	90.6	-	
Turn-On Switching Loss	E <sub>on</sub>		-	3.27	_	mJ
Turn–Off Switching Loss	E <sub>off</sub>		-	1.27	_	
Total Switching Loss	E <sub>ts</sub>		_	4.54	_	1

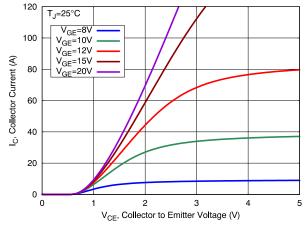
## **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = $25^{\circ}$ C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>CE</sub> = 600 V, V <sub>GE</sub> = 15 V,	-	40.5	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>	I <sub>C</sub> = 20 A, R <sub>G</sub> = 4.7 Ω, T <sub>J</sub> = 175°C	-	256	_	
Rise Time	t <sub>r</sub>		-	38.8	-	
Fall Time	t <sub>f</sub>		-	282	-	
Turn-On Switching Loss	E <sub>on</sub>		-	1.58	-	mJ
Turn-Off Switching Loss	E <sub>off</sub>		-	1.8	-	
Total Switching Loss	E <sub>ts</sub>		-	3.38	-	
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{CE} = 600 \text{ V}, V_{GE} = 15 \text{ V},$	-	46.8	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>	I <sub>C</sub> = 40 A, R <sub>G</sub> = 4.7 Ω, T <sub>J</sub> = 175°C	-	199	-	
Rise Time	t <sub>r</sub>		-	70.7	-	
Fall Time	t <sub>f</sub>		-	167	-	
Turn-On Switching Loss	E <sub>on</sub>		-	4.74	-	mJ
Turn–Off Switching Loss	E <sub>off</sub>		-	2.19	-	
Total Switching Loss	E <sub>ts</sub>		-	6.93	-	
DIODE CHARACTERISTICS						
Forward Voltage	V <sub>F</sub>	$I_F = 40 \text{ A}, \text{ T}_J = 25^{\circ}\text{C}$	-	1.98	2.36	V
		$I_F = 40 \text{ A},  \text{T}_\text{J} = 175^\circ\text{C}$	-	2.04	-	
DIODE SWITCHING CHARACTERIS	TICS, INDUCTIVE	LOAD				
Reverse Recovery Time	t <sub>rr</sub>	$V_{\rm R} = 600 \text{ V}, I_{\rm F} = 20 \text{ A},$	-	161	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>	$dI_F/dt = 500 \text{ A}/\mu \text{s}, T_J = 25^{\circ}\text{C}$	-	1773	-	nC
Reverse Recovery Energy	E <sub>rec</sub>		-	0.56	-	mJ
Peak Reverse Recovery Current	I <sub>RRM</sub>		-	25.8	-	А
Reverse Recovery Time	t <sub>rr</sub>	$V_{\rm R} = 600 \text{ V}, I_{\rm F} = 40 \text{ A},$	-	194	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>	$dI_F/dt = 500 \text{ A/}\mu\text{s}, T_J = 25^{\circ}\text{C}$	-	3123	-	nC
Reverse Recovery Energy	E <sub>rec</sub>		-	0.81	-	mJ
Peak Reverse Recovery Current	I <sub>RRM</sub>		-	35.8	-	А
Reverse Recovery Time	t <sub>rr</sub>	$V_{\rm R} = 600 \text{ V}, \text{ I}_{\rm F} = 20 \text{ A},$	-	215	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>	dl <sub>F</sub> /dt = 500 A/µs, T <sub>J</sub> = 175°C	-	2768	-	nC
Reverse Recovery Energy	E <sub>rec</sub>		-	1	_	mJ
Peak Reverse Recovery Current	I <sub>RRM</sub>		-	30.2	-	А
Reverse Recovery Time	t <sub>rr</sub>	$V_{\rm R} = 600 \text{ V}, I_{\rm F} = 40 \text{ A},$	-	261	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>	$dI_F/dt = 500 \text{ A}/\mu \text{s}, T_J = 175^{\circ}\text{C}$	-	5087	-	nC
Reverse Recovery Energy	E <sub>rec</sub>		-	1.5	-	mJ
Peak Reverse Recovery Current	I <sub>RRM</sub>	1		42.7		А

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.









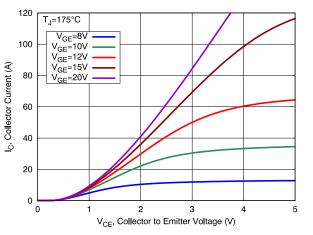


Figure 3. Output Characteristics

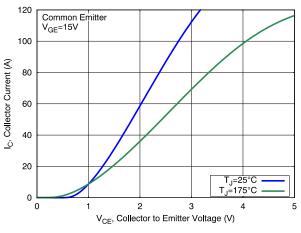


Figure 5. Saturation Characteristics

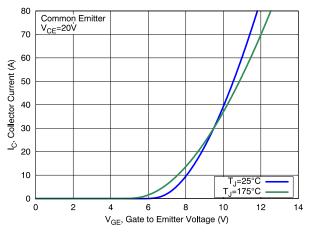
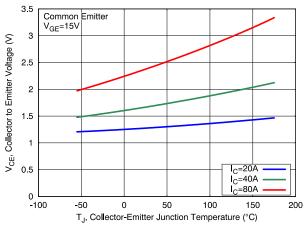


Figure 4. Transfer Characteristics





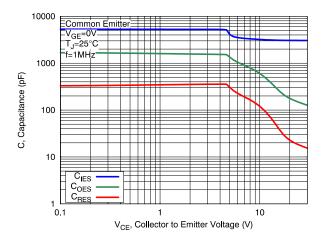


Figure 7. Capacitance Characteristics

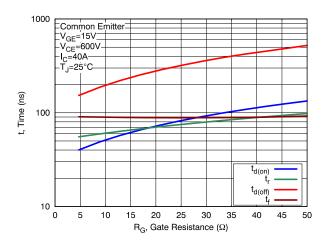


Figure 9. Switching Time vs Gate Resistance

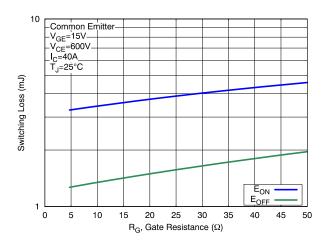


Figure 11. Switching Loss vs Gate Resistance

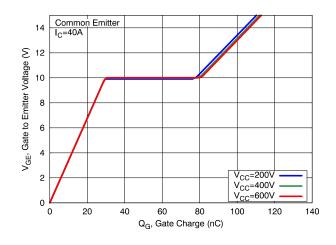


Figure 8. Gate Charge Characteristics

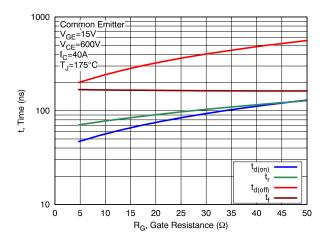


Figure 10. Switching Time vs Gate Resistance

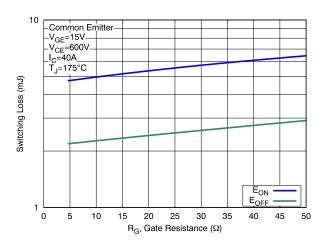
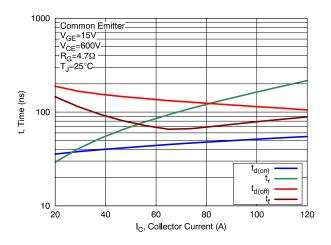
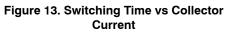
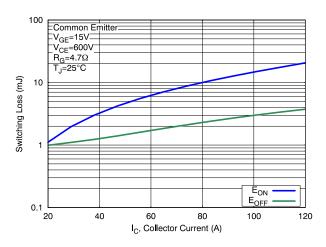


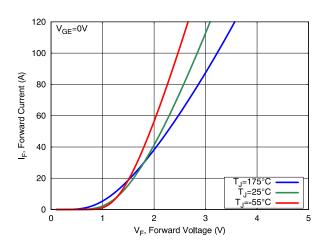
Figure 12. Switching Loss vs Gate Resistance

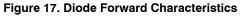












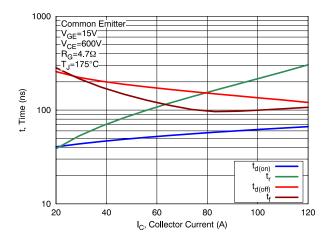


Figure 14. Switching Time vs Collector Current

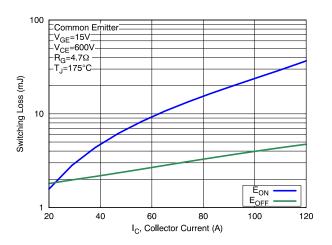


Figure 16. Switching Loss vs Collector Current

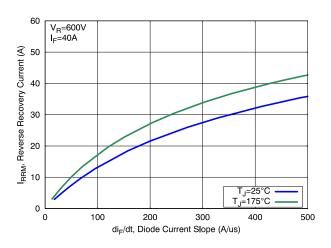
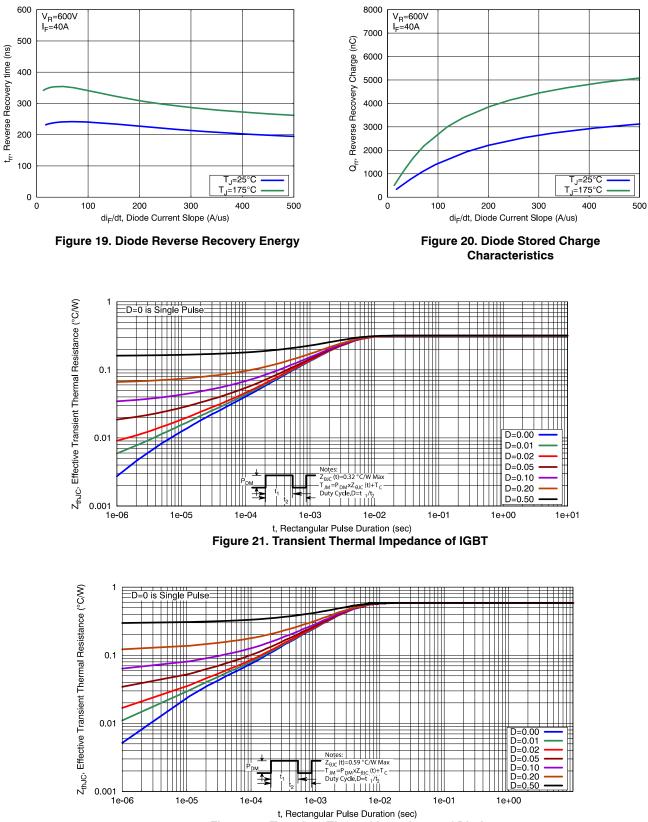
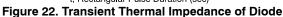
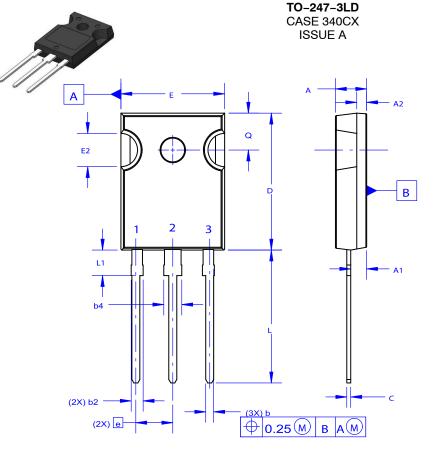


Figure 18. Diode Reverse Recovery Current









NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

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## GENERIC **MARKING DIAGRAM\*** Х



XXXXX	= Specific Device Code
Α	= Assembly Location

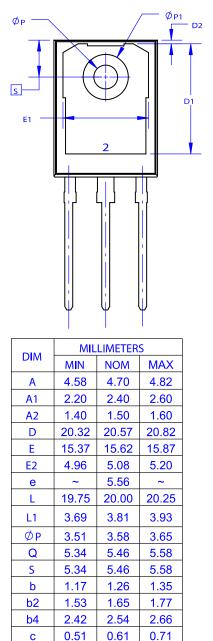
- = Assembly Location
- = Year
- ww = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	TO-247-3LD		PAGE 1 OF 1	

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DATE 06 JUL 2020



D1

D2

E1

ØP1

13.08

0.51

12.81

6.60

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0.93

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6.80

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1.35

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7.00

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